What is claimed is:

1. A method for manufacturing a mid-plane, comprising the steps of:

providing a multi-layer board having a connection assembly;

providing a layer with a channel formed therein to define a perimeter of a connector area;

bonding the layer to the multi-layer board such that the connector area overlaps the part of the connection assembly of the multi-layer board; and

removing at least a portion of the connector area in the layer to expose the connection assembly of the multi-layer board.

2. The method of claim 1, wherein the layer is bonded to the multi-layer board so as to form a space between the layer and the connection assembly of the multi-layer board.

3. The method of claim 1, wherein the layer is bonded to a conductive layer to form a metallic foil.

4. The method of claim 3, wherein the metallic foil is a single sided copper clad laminate whereby the conductive layer is formed of copper and the layer is applied to only one side of the conductive layer of copper.

5. The method of claim 1, wherein the step of removing at least a portion of the connector area is defined further as removing the connector area by depth controlled routing along the channel.

6. The method of claim 1, wherein the multi-layer board is coated with a surface finish prior to the step of bonding the layer to the multi-layer board.

7. A method for manufacturing a mid-plane, comprising the steps of:

providing two multi-layer boards with each having a connection assembly;

providing first and second layers with each having a channel formed therein to define a perimeter of a connector area;

bonding the first layer to one of the multi-layer boards and the second layer to the other one of the multi-layer boards such that the connector areas overlap the respective connection assemblys of the multi-layer boards;

bonding the multi-layer boards together to form a rigid multilayer wherein the first layer is positioned on one side of the rigid multilayer and the second layer is positioned on an opposite side of the rigid multilayer; and

removing at least a portion of the connector areas in the first and second layers to expose the respective connection assemblys.

8. The method of claim 7, wherein each of the layers are bonded to the multi-layer boards so as to form a space between the layer and the connection assembly of the multi-layer board.

9. The method of claim 7, wherein the layer is bonded to a conductive layer to form a metallic foil.

10. The method of claim 9, wherein the metallic foil is a single sided copper clad laminate whereby the conductive layer is formed of copper and the layer is applied to only one side of the layer of copper.

11. The method of claim 7, wherein the step of removing at least a portion of the connector areas is defined further as removing the connector areas by depth controlled routing along the channels.

12. The method of claim 7, wherein the multi-layer boards are coated with a surface finish prior to the step of bonding the layer to the multi-layer board.

13. A rigid multilayer, comprising:

a multi-layer board having a connection assembly;

a layer having a channel formed therein to define a perimeter of a connector area, the layer bonded to the multi-layer board such that the connector area overlaps the connection assembly of the multi-layer board.

14. The rigid multilayer of claim 13, wherein the layer has a first side in which the channel is formed and wherein the first side of the layer faces the multi-layer board.

15. The rigid multilayer of claim 13, wherein the connector area of the layer is spaced a distance from the multi-layer board.

16. The rigid multilayer of claim 13, further comprising a conductive layer extending over the layer such that the layer is positioned between the conductive layer and the multi-layer board.